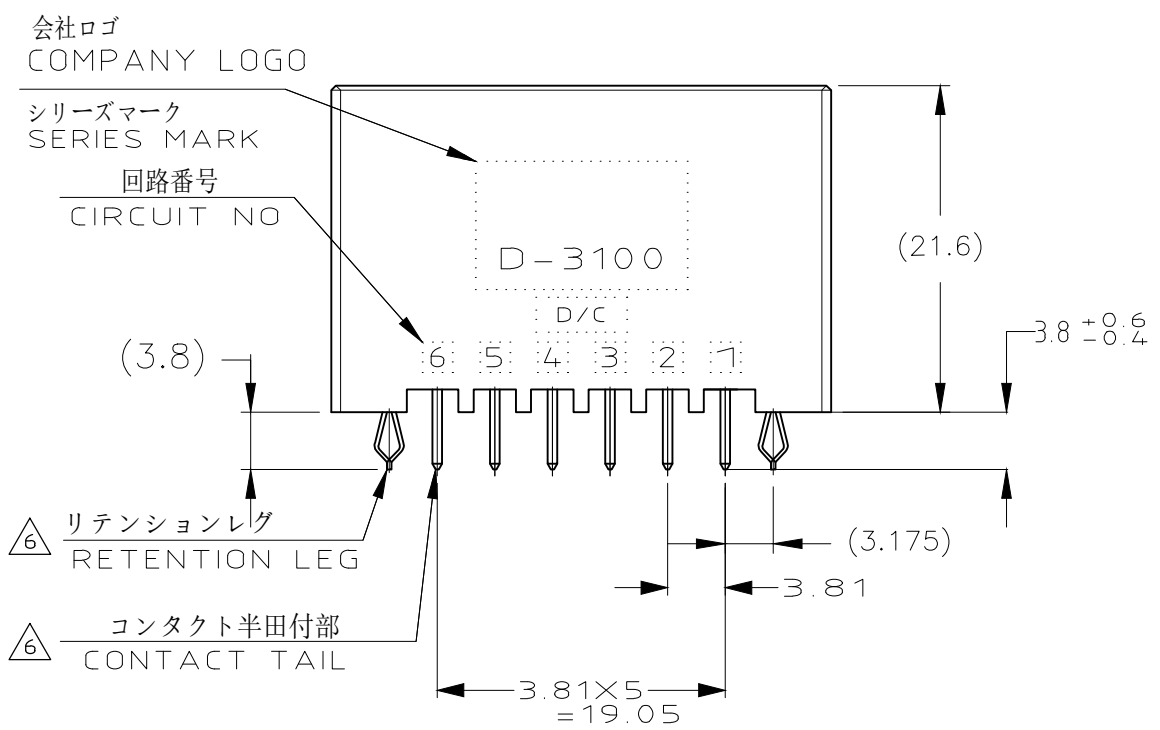
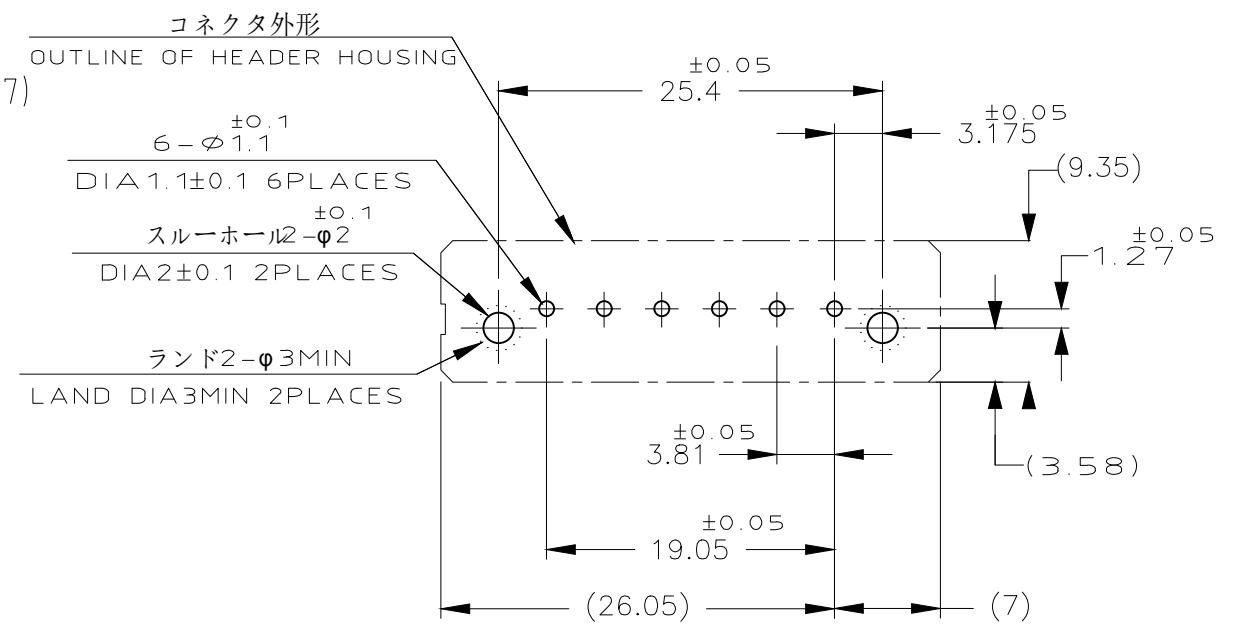
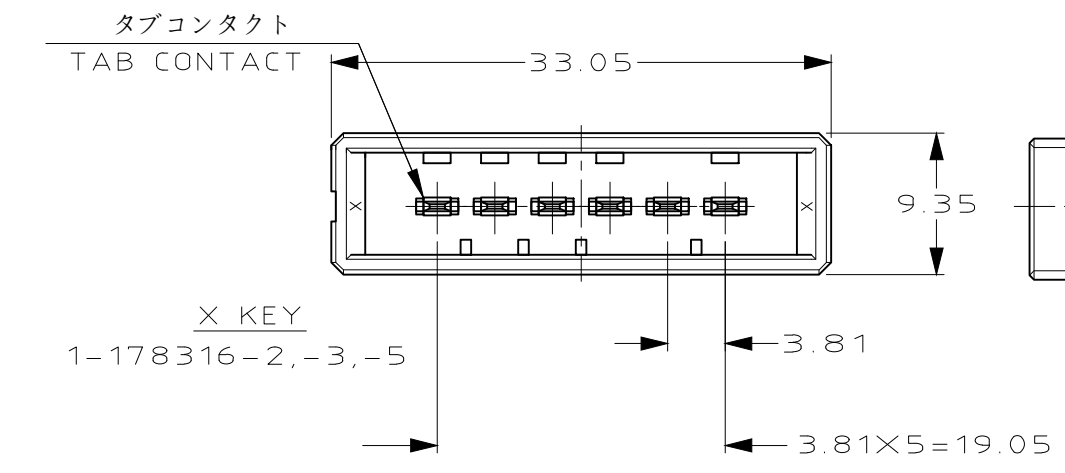


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REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C2	REVISED PER ECR-18-010496	04JUN2018	K.T	E.I

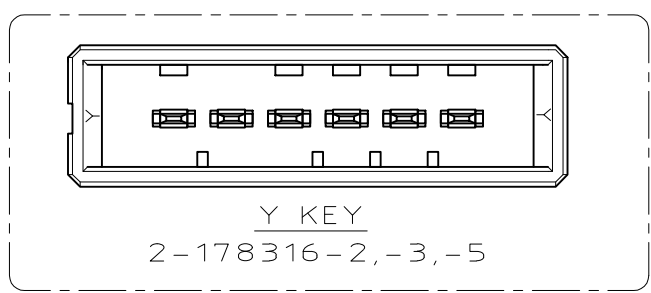


推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- ② FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
 - ③ FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
 - ④ FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - ⑤ FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- ▽ GENERAL TOLERANCE
- | | |
|------------|-------|
| ≤ 10 | ±0.3 |
| 10 < ≤ 30 | ±0.4 |
| 30 < ≤ 100 | ±0.45 |
| ANGLE | ±3° |

1. 材料 ハウジングガラス入り熱可塑性
 ポリエステル樹脂
 コンタクト銅合金
 リテンションレグ銅合金
- ② めっき コンタクト全面Ni下地
 接触部 0.38μm MIN 金めっき
 - ③ めっき コンタクト全面Ni下地
 接触部 0.76μm MIN 金めっき
 - ④ めっき コンタクト全面Ni下地
 接触部 2.0 μm MIN スズめっき
 - ⑤ めっき リテンションレグとコンタクト半田付部
 : ニッケル下地の上にスズめっき
- ▽ 一般公差
- | | |
|------------|-------|
| 10以下 | ±0.3 |
| 10を超え30以下 | ±0.4 |
| 30を超え100以下 | ±0.45 |
| 角度 | ±3° |



⑥	④	1,2-178316-5
⑥	③	1,2-178316-3
⑥	②	1,2-178316-2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN K.IKEDA 22DEC1994	TE Connectivity Ltd.		
DIMENSIONS: mm		CHK S.MANABE 10JAN1995			
TOLERANCES UNLESS OTHERWISE SPECIFIED.		APVD S.MANABE 10JAN1995	NAME 6POS SINGLE ROW VERTICAL HDR ASSY DYNAMIC 3100		
0 PLC ± -		PRODUCT SPEC 108-5349	SIZE A3		
1 PLC ± -		APPLICATION SPEC 114-5148	CAGE CODE -	DRAWING NO C-178316	RESTRICTED TO -
2 PLC ± -		MATERIAL SEE NOTE	SCALE 2:1		
3 PLC ± -		FINISH SEE NOTE	SHEET 1 OF 1		
4 PLC ± -		CUSTOMER DRAWING			
ANGLES ± -		REV C2			

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)